



STIC Search Report

EIC 3700

STIC Database Tracking Number: 1094624

TO: Timothy Eley
Location: cp2 11d06
Art Unit: 3724
Tuesday, December 02, 2003

Case Serial Number: 09/199198

From: Terry Solomon
Location: EIC 3700
CP2-2C08
Phone: 305-5932

Terrance.solomon@uspto.gov

Search Notes

No litigation found.

Sources: Lexis/Nexis and Questel-Orbit

www.lexis.com

UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT

6142138

November 7, 2000

High speed method of aligning cutting lines of a workpiece using patterns

REISSUE: January 23, 2002 - Reissue Application filed Ex. Gp.: 3723; Re. S.N. 10/053,377 (O.G. May 21, 2002)

APPL-NO: 199198 (09)

FILED-DATE: November 25, 1998

GRANTED-DATE: November 7, 2000

LEGAL-REP: Nixon Peabody LLP; Safran, David S.

ENGLISH-ABST:

Two imaging equipment are provided at a pair of cutting blade units, and the two imaging equipment image patterns at first positions in proximity to the center of a wafer at the same time. A controller drives drive mechanisms to align the wafer in such a way that current image patterns at the first positions can match with a reference pattern at the first positions. Then, the two imaging equipment are moved to positions for imaging patterns at second positions at the outer circumference of the wafer to image the patterns at the second positions. The controller drives the drive mechanisms to align the wafer in such a way that current image patterns at the second positions can match with a reference pattern at the second positions.

Segments: Abst, Appl-no, Cert-correction, Legal-rep, Legal-status, Lit-reex, Patno, Reexam-cert, Reexam-litigate, Reissue, Reissue-comment

Date/Time: Tuesday, December 2, 2003 - 8:43 AM EST

Selected file: PLUSPAT

PLUSPAT - (c) Questel-Orbit, All Rights Reserved.
Comprehensive Worldwide Patents database

** SS 1: Results 1

Query/Command : prt fu nonstop legalall

I / 1 PLUSPAT - ©QUESTEL-ORBIT - image
PN - US6142138 A 20001107 [US6142138]
TI - (A) High speed method of aligning cutting lines of a workpiece
using patterns
PA - (A) TOKYO SEIMITSU CO LTD (JP); KULICKE & SOFFA INVESTMENTS (US)
PAO - Tokyo Seimitsu Company, Ltd., Tokyo [JP]
Kulicke & Soffa Investments, Inc., Wilmington DE [US]
IN - (A) AZUMA MASAYUKI (JP); SHIMODA HIROFUMI (JP)
AP - US19919898 19981125 [1998US-0199198]
PR - JP33054097 19971201 [1997JP-0330540]
IC - (A) B28D-001/04
EC - B23D-059/00B1
B27B-031/06
B28D-005/02C10
PCL - ORIGINAL (O) : 125014000; CROSS-REFERENCE (X) : 083425200
083471300 125013010 451190000 451194000
DT - Basic
CT - US4416312; US4688540; US5842461
STG - (A) United States patent
AB - Two imaging equipment are provided at a pair of cutting blade
units, and the two imaging equipment image patterns at first
positions in proximity to the center of a wafer at the same time.
A controller drives drive mechanisms to align the wafer in such a
way that current image patterns at the first positions can match
with a reference pattern at the first positions. Then, the two
imaging equipment are moved to positions for imaging patterns at
second positions at the outer circumference of the wafer to image
the patterns at the second positions. The controller drives the
drive mechanisms to align the wafer in such a way that current
image patterns at the second positions can match with a reference
pattern at the second positions.
UP - 2000-44

I / 1 CRXX - ©CLAIMS/RRX
PN - 6,142,138 A 20001107 [US6142138]
PA - Kulicke & Soffa Investments Inc; Tokyo Seimitsu Co Ltd JP
ACT - 20011003 REASSIGNED
AGREEMENT

Assignor: TOKYO SEIMITSU CO., LTD. DATE SIGNED: 09/28/2001
KULICKE & SOFFA INVESTMENTS, INC. DATE SIGNED: 09/06/2001

Assignee: TOKYO SEIMITSU CO., LTD. 7-1, SHIMORENJAKU 9 MITAKA-SHI,
TOKYO JAPAN
KULICKE & SOFFA INVESTMENTS, INC. 300 DELAWARE AVENUE, SUITE 533
WILMINGTON DELAWARE 19801

Reel 012211/Frame 0786

Contact: NIXON PEABODY, LLP DAVID S. SAFRAN, ESQ. 8180 GREENSBORO
DRIVE SUITE 800 MCLEAN, VA 22102

2 / 3 INPADOC - @INPADOC
PN - JP 11162890 A2 19990618 [JP11162890]
TI - METHOD AND DEVICE FOR ALIGNMENT
IN - AZUMA MASAYUKI; SHIMODA HIROSHI
PA - TOKYO SEIMITSU CO LTD
AP - JP 330540/97-A 19971201 [1997JP-0330540]
PR - JP 330540/97-A 19971201 [1997JP-0330540]
IC - H01L-021/301; H01L-021/68

3 / 3 INPADOC - @INPADOC
PN - US 6142138 A 20001107 [US6142138]
TI - HIGH SPEED METHOD OF ALIGNING CUTTING LINES OF A WORKPIECE USING
PATTERNS
IN - AZUMA MASAYUKI [JP]; SHIMODA HIROFUMI [JP]
PA - TOKYO SEIMITSU CO LTD [JP]; KULICKE & SOFFA INVESTMENTS [US]
AP - US 199198/98-A 19981125 [1998US-0199198]
PR - JP 330540/97-A 19971201 [1997JP-0330540]
IC - B28D-001/04

Session finished: 02 DEC 2003 Time 14:51:55

QUESTEL.ORBIT thanks you. Hope to hear from you again soon.



Creation date: 04-03-2004

Indexing Officer: MTRUONG2 - MINH NGOC TRUONG

Team: OIPEBackFileIndexing

Dossier: 10053377

Legal Date: 11-25-1998

No.	Doccode	Number of pages
1	IIFW	1
2	SRFW	1
3	FWCLM	1
4	TRNA	2
5	DRW	7
6	SPEC	12
7	CLM	4
8	ABST	1
9	OATH	2
10	BIB	2
11	WFEE	1
12	WFEE	2
13	FRPR	25

Total number of pages: 61

Remarks:

Order of re-scan issued on